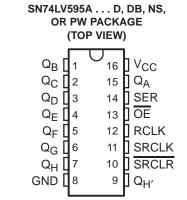
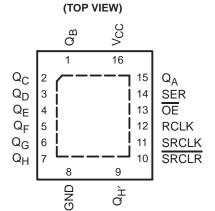
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- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 7.1 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- 8-Bit Serial-In, Parallel-Out Shift

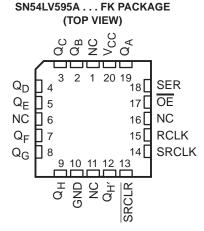
- I_{off} Supports Partial-Power-Down Mode Operation
- Shift Register Has Direct Clear
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



SN54LV595A . . . J OR W PACKAGE



SN74LV595A...RGY PACKAGE



NC - No internal connection

description/ordering information

The 'LV595A devices are 8-bit shift registers designed for 2-V to 5.5-V V_{CC} operation.

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Reel of 1000	SN74LV595ARGYR	LV595A
	colo D	Tube of 40	SN74LV595AD	11/5054
	SOIC - D	Reel of 2500	SN74LV595ADR	LV595A
4000 to 0500	SOP - NS	Reel of 2000	SN74LV595ANSR	74LV595A
-40°C to 85°C	SSOP – DB	Reel of 2000	SN74LV595ADBR	LV595A
		Tube of 90	SN74LV595APW	
	TSSOP - PW	Reel of 2000	SN74LV595APWR	LV595A
		Reel of 250	SN74LV595APWT	
	CDIP – J	Tube of 25	SNJ54LV595AJ	SNJ54LV595AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV595AW	SNJ54LV595AW
	LCCC – FK	Tube of 55	SNJ54LV595AFK	SNJ54LV595AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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description/ordering information (continued)

These devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state outputs. Separate clocks are provided for both the shift and storage register. The shift register has a direct overriding clear (\overline{SRCLR}) input, serial (SER) input, and a serial output for cascading. When the output-enable (\overline{OE}) input is high, all outputs except $Q_{H'}$ are in the high-impedance state.

Both the shift register clock (SRCLK) and storage register clock (RCLK) are positive-edge triggered. If both clocks are connected together, the shift register always is one clock pulse ahead of the storage register.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

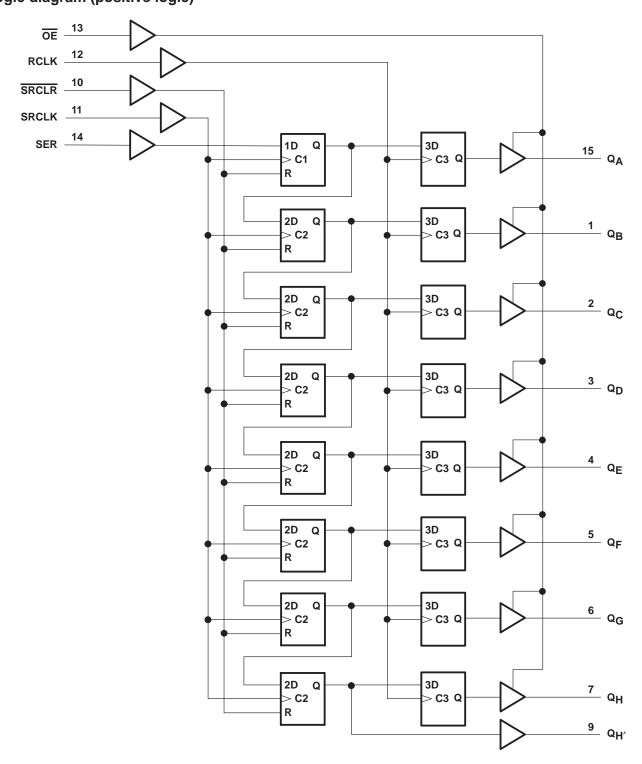
These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

FUNCTION TABLE

		INPUTS			FUNCTION
SER	SRCLK	SRCLR	RCLK	OE	FUNCTION
Х	Х	Х	Х	Н	Outputs Q _A –Q _H are disabled.
Х	Χ	Χ	Χ	L	Outputs Q _A –Q _H are enabled.
Х	Χ	L	Χ	Χ	Shift register is cleared.
L	1	Н	Х	Х	First stage of the shift register goes low. Other stages store the data of previous stage, respectively.
Н	1	Н	Х	Х	First stage of the shift register goes high. Other stages store the data of previous stage, respectively.
Х	Х	Х	1	Χ	Shift-register data is stored in the storage register.



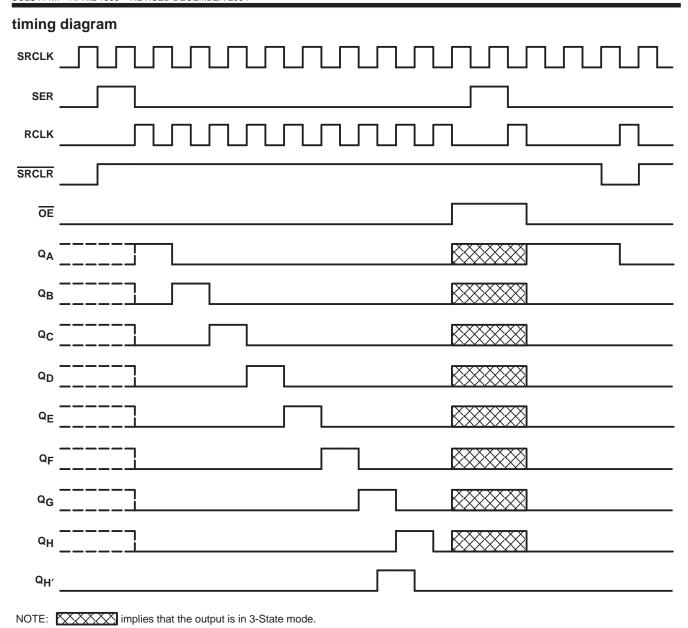
logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, NS, PW, RGY, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} –0.5	\mbox{V} to 7 \mbox{V}
Input voltage range, V _I (see Note 1) –0.5	\mbox{V} to 7 \mbox{V}
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)0.5	V to $7\ V$
Output voltage range applied in the high or low state, VO (see Notes 1 and 2)0.5 V to VCO	+ 0.5 V
Input clamp current, I _{IK} (V _I < 0)	-20 mA
Output clamp current, I _{OK} (V _O < 0)	-50 mA
Continuous output current, I _O (V _O = 0 to V _{CC})	$\pm 35~\text{mA}$
Continuous current through V _{CC} or GND	$\pm 70~\text{mA}$
Package thermal impedance, $\hat{\theta}_{JA}$ (see Note 3): D package	73°C/W
(see Note 3): DB package	82°C/W
(see Note 3): NS package	64°C/W
(see Note 3): PW package	08°C/W
(see Note 4): RGY package	39°C/W
Storage temperature range, T _{stg} –65°C t	o 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.
- 4. The package thermal impedance is calculated in accordance with JESD 51-5.



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recommended operating conditions (see Note 5)

			SN54L	.V595A	SN74I	V595A	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
.,		V _{CC} = 2.3 V to 2.7 V	V _{CC} ×0.7		V _{CC} ×0.7		.,
V_{IH}	High-level input voltage	V _{CC} = 3 V to 3.6 V	V _{CC} × 0.7		$V_{CC} \times 0.7$		V
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.7		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
.,		V _{CC} = 2.3 V to 2.7 V		V _{CC} ×0.3		V _{CC} × 0.3	
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		V _{CC} ×0.3		V _{CC} × 0.3	V
		V _{CC} = 4.5 V to 5.5 V		V _{CC} ×0.3		V _{CC} ×0.3	
٧ı	Input voltage	•	0	5.5	0	5.5	V
.,		High or low state	0	⁴ √VCC	0	VCC	
VO	Output voltage	3-state	0 /	5.5	0	5.5	V
		V _{CC} = 2 V	5	-50		-50	μΑ
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0	-2		-2	
ЮН	High-level output current	V _{CC} = 3 V to 3.6 V	Q	-8		-8	mA
		V _{CC} = 4.5 V to 5.5 V		-16		-16	
		V _{CC} = 2 V		50		50	μΑ
		V _{CC} = 2.3 V to 2.7 V		2		2	
lOL	Low-level output current	V _{CC} = 3 V to 3.6 V		8		8	mA
		V _{CC} = 4.5 V to 5.5 V		16		16	
		V _{CC} = 2.3 V to 2.7 V		200		200	
Δt/Δν	Input transition rise or fall rate	V _{CC} = 3 V to 3.6 V		100		100	ns/V
		V _{CC} = 4.5 V to 5.5 V		20		20	
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEGT COMPLETIONS	.,	SN54	4LV595A	SN74LV5	95A	
PAR	RAMETER	TEST CONDITIONS	Vcc	MIN	TYP MAX	MIN T	YP MAX	UNIT
		I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1		V _{CC} -0.1		
		$I_{OH} = -2 \text{ mA}$	2.3 V	2		2		
	$Q_{H'}$	$I_{OH} = -6 \text{ mA}$	2.1/	2.48		2.48		V
VOH	Q_A-Q_H	I _{OH} = -8 mA	3 V	2.48		2.48		V
	$Q_{H'}$	$I_{OH} = -12 \text{ mA}$	451/	3.8		3.8		
	Q _A -Q _H	I _{OH} = -16 mA	4.5 V	3.8		3.8		
		I _{OL} = 50 μA	2 V to 5.5 V		0.1		0.1	
		$I_{OL} = 2 \text{ mA}$	2.3 V		0.4		0.4	
\ \/ - ·	Q _H ′	I _{OL} = 6 mA	2.1/		0.44		0.44	V
VOL	Q _A -Q _H	I _{OL} = 8 mA	3 V		0.44		0.44	V
	$Q_{H'}$	I _{OL} = 12 mA	451/	100	0.55		0.55	
	Q_A-Q_H	I _{OL} = 16 mA	4.5 V	A.	0.55		0.55	
Ц		V _I = 5.5 V or GND	0 to 5.5 V		±1		±1	μΑ
loz		$V_O = V_{CC}$ or GND, $Q_A - Q_H$	5.5 V		±5		±5	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		20		20	μΑ
l _{off}		V_I or $V_O = 0$ to 5.5 V	0		5		5	μΑ
Ci		V _I = V _{CC} or GND	3.3 V		3.5	3	3.5	pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

			T _A =	25°C	SN54L	V595A	SN74L\	/595A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		SRCLK high or low	7		7.5		7.5		
t _w	Pulse duration	RCLK high or low	7		7.5	FW	7.5		ns
		SRCLR low	6		6.5	N.	6.5		
		SER before SRCLK↑	5.5		5.5 4	S	5.5		
	Outro Cara	SRCLK↑ before RCLK↑†	8		9	,	9		
t _{su}	Setup time	SRCLR low before RCLK↑	8.5		9.5		9.5		ns
		SRCLR high (inactive) before SRCLK↑	4		4		4		
th	Hold time	SER after SRCLK↑	1.5		1.5		1.5		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

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timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			$T_A = 1$	25°C	SN54L\	/595A	SN74L\	/595A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		SRCLK high or low	5.5		5.5		5.5		
t _w	Pulse duration	RCLK high or low	5.5		5.5	EW	5.5		ns
		SRCLR low	5		5	F	5		
		SER before SRCLK↑	3.5		3.5	2	3.5		
١.	Catum times	SRCLK↑ before RCLK↑†	8		8.5		8.5		
tsu	Setup time	SRCLR low before RCLK↑	8		9		9		ns
		SRCLR high (inactive) before SRCLK↑	3		3		3		
th	Hold time	SER after SRCLK↑	1.5		1.5		1.5		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A =	25°C	SN54L	V595A	SN74L\	/595A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		SRCLK high or low	5		5		5		
t _w	Pulse duration	RCLK high or low	5		5	FW	5		ns
		SRCLR low	5.2		5.2	F	5.2		
		SER before SRCLK↑	3		3 4	2	3		
	Outros Cara	SRCLK↑ before RCLK↑†	5		5		5		
t _{su}	Setup time	SRCLR low before RCLK↑	5		5		5		ns
		SRCLR high (inactive) before SRCLK↑	2.5		2.5		2.5		
th	Hold time	SER after SRCLK↑	2		2		2		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T	_A = 25°C	;	SN54L	√595A	SN74L	/595A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	65*	80*		45*		45		MHz
fmax			C _L = 50 pF	60	70		40		40		IVIHZ
t _{PLH}	DOLK	0 - 0 -			8.4*	14.2*	1*	15.8*	1	15.8	
t _{PHL}	RCLK	Q_A – Q_H			8.4*	14.2*	1*	15.8*	1	15.8	
^t PLH	SRCLK	0			9.4*	19.6*	1*	22.2*	1	22.2	
^t PHL	SKULK	$Q_{H'}$			9.4*	19.6*	1*	22.2*	1	22.2	
^t PHL	SRCLR	Q _H ′	C _L = 15 pF		8.7*	14.6*	1*	16.3*	1	16.3	ns
^t PZH	ŌĒ	0 - 0 -			8.2*	13.9*	1*	15*	1	15	
t _{PZL}	OE	Q_A – Q_H			10.9*	18.1*	1*	20.3*	1	20.3	
^t PHZ	ŌĒ	0 - 0 -			8.3*	13.7*	1*,	15.6*	1	15.6	
^t PLZ	OE	Q_A – Q_H			9.2*	15.2*	15	16.7*	1	16.7	
^t PLH	RCLK	0 - 0 -			11.2	17.2	81	19.3	1	19.3	
^t PHL	RCLK	Q_A-Q_H			11.2	17.2	2 1	19.3	1	19.3	
^t PLH	SRCLK	0			13.1	22.5	1	25.5	1	25.5	
^t PHL	SKULK	Q _H ′			13.1	22.5	1	25.5	1	25.5	
^t PHL	SRCLR	$Q_{H'}$	$C_L = 50 pF$		12.4	18.8	1	21.1	1	21.1	ns
^t PZH	ŌĒ	0 - 0 -			10.8	17	1	18.3	1	18.3	
tPZL	OE	Q_A – Q_H			13.4	21	1	23	1	23	
^t PHZ	ŌĒ	0.00			12.2	18.3	1	19.5	1	19.5	
tPLZ	OE .	Q_A – Q_H			14	20.9	1	22.6	1	22.6	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	_A = 25°C	;	SN54L	V595A	SN74L	√595A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
,			C _L = 15 pF	80*	120*		70*		70		N.41.1-
f _{max}			C _L = 50 pF	55	105		50		50		MHz
^t PLH	DOLK	00			6*	11.9*	1*	13.5*	1	13.5	
^t PHL	RCLK	Q _A –Q _H			6*	11.9*	1*	13.5*	1	13.5	
^t PLH	CDCI IX				6.6*	13*	1*	15*	1	15	
^t PHL	SRCLK	Q _H ′			6.6*	13*	1*	15*	1	15	
^t PHL	SRCLR	Q _H ′	C _L = 15 pF		6.2*	12.8*	1*	13.7*	1	13.7	ns
^t PZH	ŌĒ	0 0			6*	11.5*	1*	13.5*	1	13.5	
^t PZL	OE	Q _A –Q _H			7.8*	11.5*	1*	13.5*	1	13.5	
^t PHZ	ŌĒ	0.00			6.1*	14.7*	1*	15.2*	1	15.2	
^t PLZ	OE	Q _A –Q _H			6.3*	14.7*	150	15.2*	1	15.2	
^t PLH	RCLK	0.00			7.9	15.4	81	17	1	17	
^t PHL	RCLK	Q_A-Q_H			7.9	15.4	2 1	17	1	17	
^t PLH	CDCL IC	0			9.2	16.5	1	18.5	1	18.5	
^t PHL	SRCLK	Q _H ′			9.2	16.5	1	18.5	1	18.5	
^t PHL	SRCLR	Q _H ′	$C_L = 50 pF$		9	16.3	1	17.2	1	17.2	ns
^t PZH	ŌĒ	0 0			7.8	15	1	17	1	17	
t _{PZL}	OE	Q _A –Q _H]		9.6	15	1	17	1	17	
^t PHZ	ŌĒ	0.4-011			8.1	15.7	1	16.2	1	16.2	
^t PLZ	OL.	Q _A –Q _H			9.3	15.7	1	16.2	1	16.2	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T,	4 = 25°C	;	SN54L\	/595A	SN74L	/595A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
4			C _L = 15 pF	135*	170*		115*		115		NAL 1-
f _{max}			C _L = 50 pF	120	140		95		95		MHz
t _{PLH}	DOLK	0 0			4.3*	7.4*	1*	8.5*	1	8.5	
t _{PHL}	RCLK	Q_A – Q_H]		4.3*	7.4*	1*	8.5*	1	8.5	
t _{PLH}	CDCI IX	0			4.5*	8.2*	1*	9.4*	1	9.4	
t _{PHL}	SRCLK	$Q_{H'}$]		4.5*	8.2*	1*	9.4*	1	9.4	
^t PHL	SRCLR	$Q_{H'}$	C _L = 15 pF		4.5*	8*	1*	9.1*	1	9.1	ns
^t PZH	ŌĒ	0 0]		4.3*	8.6*	1*	10*	1	10	
tPZL	OE	Q_A – Q_H]		5.4*	8.6*	1*	//10*	1	10	
^t PHZ	ŌĒ	0 . 0]		2.4*	6*	1*	7.1*	1	7.1	
t _{PLZ}	OE	Q _A –Q _H			2.7*	5.1*	18	7.2*	1	7.2	
^t PLH	DOLK	0 - 0 -			5.6	9.4	81	10.5	1	10.5	
^t PHL	RCLK	Q_A-Q_H]		5.6	9.4	2 1	10.5	1	10.5	
^t PLH	SRCLK	0			6.4	10.2	1	11.4	1	11.4	
^t PHL	SKCLK	Q _H ′]		6.4	10.2	1	11.4	1	11.4	
^t PHL	SRCLR	$Q_{H'}$	$C_L = 50 pF$		6.4	10	1	11.1	1	11.1	ns
^t PZH		0 0]		5.7	10.6	1	12	1	12	
tPZL	ŌE	Q _A –Q _H]		6.8	10.6	1	12	1	12	
^t PHZ	ŌĒ	04.00]		3.5	10.3	1	11	1	11	
t _{PLZ}	OE .	Q _A –Q _H		·	3.4	10.3	1	11	1	11	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 6)

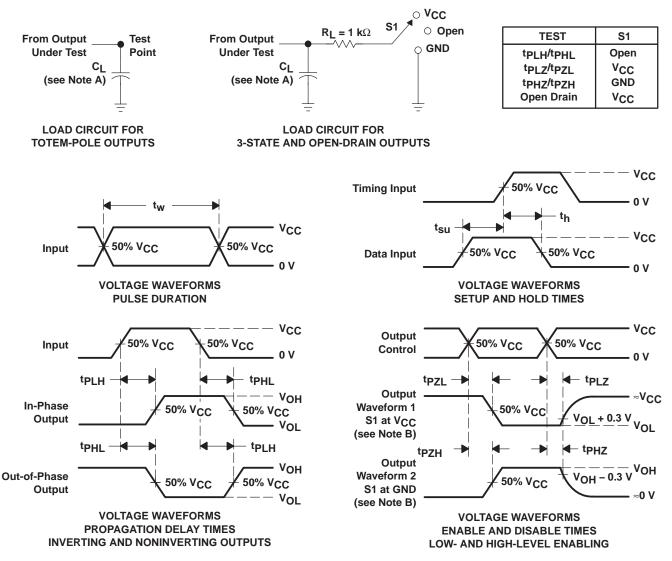
	DADAMETED	SN	74LV595	iΑ	LINUT
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic VOL		0.3		V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.2		V
VOH(V)	Quiet output, minimum dynamic VOH		2.8		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 6: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS		VCC	TYP	UNIT
<u> </u>	Dower discinction conscitones	C. F0 nF	f 40 MH I-	3.3 V	111	~F
Cpd	Power dissipation capacitance	$C_L = 50 \text{ pF},$	f = 10 MHz	5 V	114	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpz and tpzH are the same as ten.
- G. t_{PHL} and t_{PLH} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







ti.com 25-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV595AD	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74LV595ADBR	ACTIVE	SSOP	DB	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74LV595ADR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74LV595ANSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74LV595APWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV595APWT	ACTIVE	TSSOP	PW	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV595ARGYR	ACTIVE	QFN	RGY	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

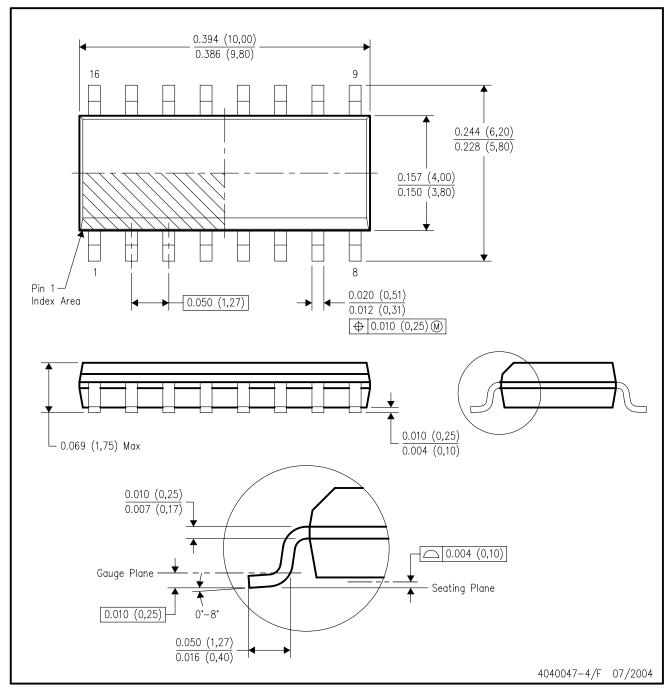
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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D (R-PDSO-G16)

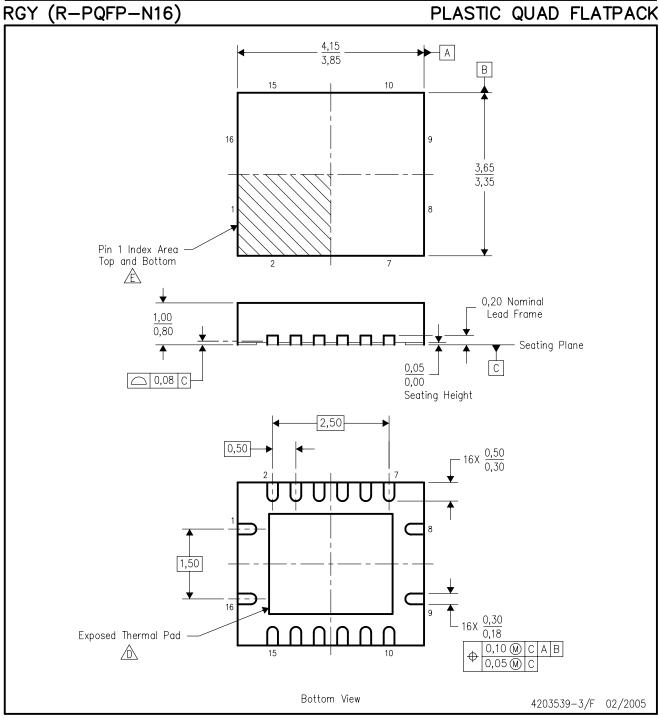
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- F. Package complies to JEDEC MO-241 variation BB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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